

φ0.15, φ0.20 Micro-Hole Drilling Performance

φ0.15, φ0.20 ドリル 加工事例

用途: 半導体パッケージ用、ビルドアップ用内層コア材 等 FBGA、BGA、for HDI etc...

Drilling Condition 加工条件

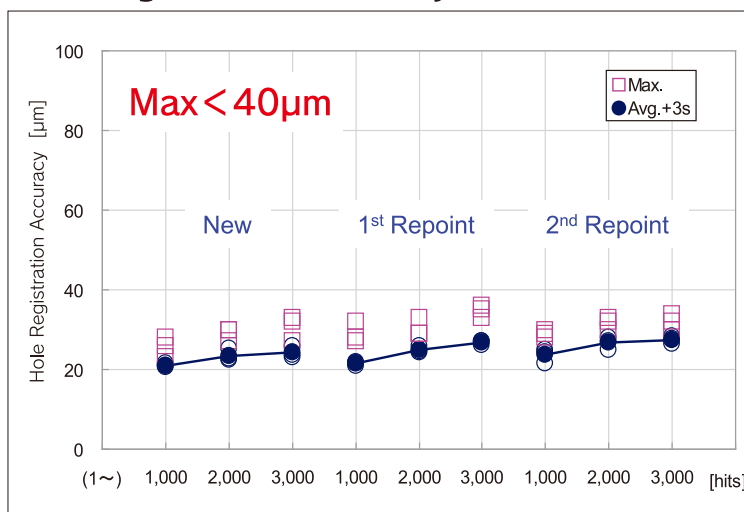
φ0.15

Work Material : BT-HL832HS t0.8(Double Sided) x 2 stack height

S : 300,000 min⁻¹ F : 3.0 m/min f : 10 μm/rev

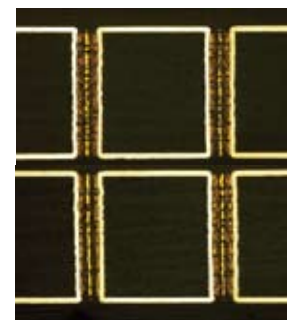
Set Life : 3,000 hits x Reprint 2 times = Total 9,000 hits

Hole Registration Accuracy 穴位置精度



Hole Wall Quality at 3,000th hit 内壁粗さ

2nd Reprint Max < 9μm



Drilling Condition 加工条件

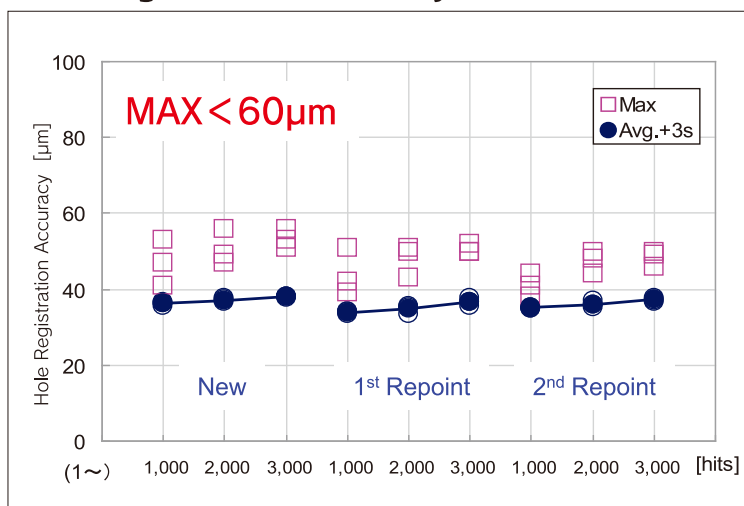
φ0.20

Work Material : MCL-E-679FG(R) t0.8(Double Sided) x 4 stack height

S : 200,000 min⁻¹ F : 2.4m/min f : 12 μm/rev

Set Life : 3,000 hits x Reprint 2 times = Total 9,000 hits

Hole Registration Accuracy 穴位置精度



Hole Wall Quality at 3,000th hit 内壁粗さ

2nd Reprint Max < 10μm

